description

These 8-bit D-type transparent latches are designed specifically for storing the contents of the input data bus, plus reading back the stored data onto the input data bus. In addition, they provide a 3-state buffer-type output and are easily utilized in bus-structured applications.

While the latch enable (LE) is high, the Q outputs of the SN74ALS666 follow the data (D) inputs. The Q̅ outputs of the SN74ALS667 provide the inverse of the data applied to its D inputs. The Q or Q̅ output of both devices is in the high-impedance state if either output-enable (OE1 or OE2) input is at a high logic level.

Read back is provided through the read-back control (OERB) input. When OERB is taken low, the data present at the output of the data latches passes back onto the input data bus. When OERB is taken high, the output of the data latches is isolated from the D inputs. OERB does not affect the internal operation of the latches; however, caution should be exercised to avoid a bus conflict.

The SN74ALS666 and SN74ALS667 are characterized for operation from 0°C to 70°C.
logic symbols †

† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
logic diagrams (positive logic)

![Logic Diagram for SN74ALS666](image1)

![Logic Diagram for SN74ALS667](image2)
SN74ALS666, SN74ALS667
8-BIT D-TYPE TRANSPARENT READ-BACK LATCHES
WITH 3-STATE OUTPUTS

Timing diagram

- Data Bus
- Input Data
- Read Back
- Input Data
- LE
- OERB
- Q

CLR = H, PRE = H, OE1 = L, OE2 = L.
† This setup time ensures the read-back circuit does not create a conflict on the input data bus.

Absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

- Supply voltage, VCC
- Input voltage, V_I (all inputs except D inputs)
- Voltage applied to D inputs and to disabled 3-state outputs
- Operating free-air temperature range, T_A: SN74ALS666, SN74ALS667
- Storage temperature range

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended operating conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>SN74ALS666</th>
<th>SN74ALS667</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC</td>
<td>MIN</td>
<td>NOM</td>
<td>MAX</td>
</tr>
<tr>
<td>V_IH</td>
<td>Q</td>
<td>2</td>
<td>V</td>
</tr>
<tr>
<td>V_IL</td>
<td>Q</td>
<td>0.8</td>
<td>V</td>
</tr>
<tr>
<td>I_OH</td>
<td>Q</td>
<td>-2.6</td>
<td>mA</td>
</tr>
<tr>
<td>I_OH</td>
<td>D</td>
<td>-0.4</td>
<td>mA</td>
</tr>
<tr>
<td>I_OL</td>
<td>Q</td>
<td>24</td>
<td>mA</td>
</tr>
<tr>
<td>I_OL</td>
<td>D</td>
<td>8</td>
<td>mA</td>
</tr>
<tr>
<td>I_W</td>
<td>LE high</td>
<td>10</td>
<td>ns</td>
</tr>
<tr>
<td>I_W</td>
<td>CLR low</td>
<td>10</td>
<td>ns</td>
</tr>
<tr>
<td>I_W</td>
<td>PRE low</td>
<td>10</td>
<td>ns</td>
</tr>
<tr>
<td>I_SU</td>
<td>Data before LE↓</td>
<td>10</td>
<td>ns</td>
</tr>
<tr>
<td>I_SU</td>
<td>Data before OERB↓</td>
<td>10</td>
<td>ns</td>
</tr>
<tr>
<td>I_H</td>
<td>Hold time, data after LE↓</td>
<td>5</td>
<td>ns</td>
</tr>
<tr>
<td>T_A</td>
<td>Operating free-air temperature</td>
<td>0</td>
<td>70</td>
</tr>
</tbody>
</table>
### Electrical Characteristics

#### Over Recommended Operating Free-Air Temperature Range

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Test Conditions</th>
<th>SN74ALS666</th>
<th>SN74ALS667</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{IK})</td>
<td>(V_{CC} = 4.5, V), (I_I = -18, \text{mA})</td>
<td>(-2.4)</td>
<td>(-2.2)</td>
<td>(V)</td>
</tr>
<tr>
<td>(V_{OH})</td>
<td>All outputs (V_{CC} = 4.5, \text{V to 5.5, V}), (I_{OH} = -0.4, \text{mA})</td>
<td>(2.0)</td>
<td>(2.4)</td>
<td>(V)</td>
</tr>
<tr>
<td>(V_{OH})</td>
<td>Q or (\overline{Q}) (V_{CC} = 4.5, \text{V}), (I_{OH} = -2.6, \text{mA})</td>
<td>(2.0)</td>
<td>(2.4)</td>
<td>(V)</td>
</tr>
<tr>
<td>(I_{OL})</td>
<td>D inputs (V_{CC} = 4.5, \text{V}), (I_{OL} = 4, \text{mA})</td>
<td>(0.25)</td>
<td>(0.25)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_{OL})</td>
<td>Q or (\overline{Q}) (V_{CC} = 4.5, \text{V}), (I_{OL} = 8, \text{mA})</td>
<td>(0.35)</td>
<td>(0.35)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_{OL})</td>
<td>Q or (\overline{Q}) (V_{CC} = 4.5, \text{V}), (I_{OL} = 12, \text{mA})</td>
<td>(0.45)</td>
<td>(0.45)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_{OL})</td>
<td>Q or (\overline{Q}) (V_{CC} = 4.5, \text{V}), (V_O = 2.7, \text{V})</td>
<td>(20)</td>
<td>(20)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_{OL})</td>
<td>Q or (\overline{Q}) (V_{CC} = 5.5, \text{V}), (V_O = 0.4, \text{V})</td>
<td>(-20)</td>
<td>(-20)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_I)</td>
<td>D inputs (V_{CC} = 5.5, \text{V}), (V_I = 5.5, \text{V})</td>
<td>(0.1)</td>
<td>(0.1)</td>
<td>(\text{mA})</td>
</tr>
<tr>
<td>(I_I)</td>
<td>All others (V_{CC} = 5.5, \text{V}), (V_I = 7, \text{V})</td>
<td>(0.1)</td>
<td>(0.1)</td>
<td>(\text{mA})</td>
</tr>
<tr>
<td>(I_{IH})</td>
<td>D inputs (V_{CC} = 5.5, \text{V}), (V_I = 2.7, \text{V})</td>
<td>(20)</td>
<td>(20)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_{IH})</td>
<td>All others (V_{CC} = 5.5, \text{V}), (V_I = 2.7, \text{V})</td>
<td>(20)</td>
<td>(20)</td>
<td>(\mu\text{A})</td>
</tr>
<tr>
<td>(I_{IL})</td>
<td>D inputs (V_{CC} = 5.5, \text{V}), (V_I = 0.4, \text{V})</td>
<td>(-0.1)</td>
<td>(-0.1)</td>
<td>(\text{mA})</td>
</tr>
<tr>
<td>(I_{IL})</td>
<td>All others (V_{CC} = 5.5, \text{V}), (V_I = 0.4, \text{V})</td>
<td>(-0.1)</td>
<td>(-0.1)</td>
<td>(\text{mA})</td>
</tr>
<tr>
<td>(I_{OS})</td>
<td>(V_{CC} = 5.5, \text{V}), (V_O = 2.25, \text{V})</td>
<td>(-30)</td>
<td>(-112)</td>
<td>(\text{mA})</td>
</tr>
</tbody>
</table>

\[\dagger\] All typical values are at \(V_{CC} = 5\, \text{V}\), \(T_A = 25^\circ\text{C}\).

\[\ddagger\] For I/O ports (\(Q_A\) through \(Q_J\)), the parameters \(I_{IH}\) and \(I_{IL}\) include the off-state output current.

\[\S\] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, \(I_{OS}\).
## Switching Characteristics (See Figure 1)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>FROM (INPUT)</th>
<th>TO (OUTPUT)</th>
<th>V&lt;sub&gt;CC&lt;/sub&gt; = 4.5 V to 5.5 V, C&lt;sub&gt;L&lt;/sub&gt; = 50 pF, T&lt;sub&gt;A&lt;/sub&gt; = MIN to MAX†</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>t&lt;sub&gt;PLH&lt;/sub&gt;</td>
<td>D</td>
<td>O</td>
<td>SN74ALS666</td>
<td>MIN MAX</td>
</tr>
<tr>
<td>t&lt;sub&gt;PHL&lt;/sub&gt;</td>
<td>LE</td>
<td>O</td>
<td></td>
<td>6-21</td>
</tr>
<tr>
<td>t&lt;sub&gt;PHL&lt;/sub&gt;</td>
<td>CLR</td>
<td>D</td>
<td></td>
<td>9-29</td>
</tr>
<tr>
<td>t&lt;sub&gt;PHL&lt;/sub&gt;</td>
<td>PRE</td>
<td>O</td>
<td></td>
<td>7-22</td>
</tr>
<tr>
<td>t&lt;sub&gt;en&lt;/sub&gt; ‡</td>
<td>OE1, OE2</td>
<td>D</td>
<td></td>
<td>4-21</td>
</tr>
<tr>
<td>t&lt;sub&gt;dis&lt;/sub&gt; §</td>
<td>OE1, OE2</td>
<td>O</td>
<td></td>
<td>1-14</td>
</tr>
</tbody>
</table>

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ t<sub>en</sub> = t<sub>ZH</sub> or t<sub>ZL</sub>
§ t<sub>dis</sub> = t<sub>HZ</sub> or t<sub>LZ</sub>
PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT FOR Q OR Q OUTPUTS

LOAD CIRCUIT FOR D OUTPUTS

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES:
A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses have the following characteristics: PRR \leq 1 \text{ MHz}, t_r = t_f = 2 \text{ ns}, duty cycle = 50%.
D. When measuring propagation delay times of 3-state outputs, switch S1 is open.

Figure 1. Load Circuits and Voltage Waveforms
## PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status (1)</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>PIns</th>
<th>Package Qty</th>
<th>Eco Plan (2)</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp (3)</th>
<th>Op Temp (°C)</th>
<th>Device Marking (4/5)</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>SN74ALS666DW</td>
<td>ACTIVE</td>
<td>SOIC DW</td>
<td>24 25</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-1-260C-UNLIM</td>
<td>0 to 70</td>
<td>ALS666</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>SN74ALS666DWE4</td>
<td>ACTIVE</td>
<td>SOIC DW</td>
<td>24 25</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-1-260C-UNLIM</td>
<td>0 to 70</td>
<td>ALS666</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>SN74ALS666DG4</td>
<td>ACTIVE</td>
<td>SOIC DW</td>
<td>24 25</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-1-260C-UNLIM</td>
<td>0 to 70</td>
<td>ALS666</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>SN74ALS667DW</td>
<td>ACTIVE</td>
<td>SOIC DW</td>
<td>24 25</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>CU NIPDAU</td>
<td>Level-1-260C-UNLIM</td>
<td>0 to 70</td>
<td>ALS667</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check [http://www.ti.com/productcontent](http://www.ti.com/productcontent) for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.
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NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
D. Falls within JEDEC MS–013 variation AD.
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